What Is Claimed Is:

A method of fabricating a liquid crystal display panel, comprising the steps
 of:

preparing an upper substrate and a lower substrate;

bonding the upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and
eliminating the exposed surfaces of the bonded upper and lower
substrates.

- 2. The method according to claim 1, wherein the step of cleaning exposed surfaces includes dry-etching.
- 3. The method according to claim 1, wherein the step of eliminating the exposed surfaces includes wet-etching.
- 4. The method according to claim 1, further including the steps of: forming a thin film transistor on the lower substrate; forming a protective layer on the lower substrate; and forming a pixel electrode on the protective layer to electrically contact the thin film transistor.
- 5. The method according to claim 4, wherein the pixel electrode is formed
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of a transparent conductive material including indium-tin-oxide (ITO), indium-zinc-oxide (IZO) and indium-tin-zinc-oxide (ITZO).

- 6. The method according to claim 4, wherein the protective layer is formed of an organic insulating material including an acrylic organic compound,

 Teflon7, benzocyclobutene (BCB), Cytop7 and perfluorocyclobutane (PFCB).
- 7. The method according to claim 4, wherein the step of forming the thin film transistor includes:

forming a gate electrode on the lower substrate;

forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and forming a source electrode and a drain electrode on the active layer.

- 8. The method according to claim 7, wherein the source electrode and drain electrode contact the gate insulating film.
- 9. The method according to claim 7, wherein the pixel electrode contacts parallel and inclined surfaces of the drain electrode.
- 10. A method of fabricating a liquid crystal display panel, comprising the steps of:

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bonding an upper substrate to a lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and
removing the exposed surfaces of the bonded upper and lower
substrates.

- 11. The method according to claim 10, wherein the step of cleaning exposed surfaces includes dry-etching.
- 12. The method according to claim 10, wherein the step of removing the exposed surfaces includes wet-etching.
- 13. The method according to claim 10, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.
- 14. A method of fabricating a liquid crystal display panel, comprising the steps of:

forming a gate electrode on a lower substrate;

forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and

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forming a source electrode and a drain electrode on the active layer;

bonding an upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and
removing the exposed surfaces of the bonded upper and lower
substrates.

- 15. The method according to claim 14, wherein the step of cleaning exposed surfaces includes dry-etching.
- 16. The method according to claim 14, wherein the step of removing the exposed surfaces includes wet-etching.
- 17. The method according to claim 14, further including the steps of forming a protective layer on the lower substrate; and forming a pixel electrode on the protective layer to electrically contact the drain electrode.
- 18. The method according to claim 17, wherein the pixel electrode is formed of a transparent conductive material including indium-tin-oxide (ITO), indium-zinc-oxide (IZO) and indium-tin-zinc-oxide (ITZO).

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- 19. The method according to claim 17, wherein the protective layer is formed of an organic insulating material including an acrylic organic compound,

 Teflon7, benzocyclobutene (BCB), Cytop7 and perfluorocyclobutane (PFCB).
- 20. The method according to claim 14, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

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